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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: KIYOSHI DEMIZU ET AL

Serial No.: Not Yet Assigned Group Art Unit:

Filed: December 27, 2001 Examiner:

CAM#: 29368.029

Title: SEMICONDUCTOR WAFER AND DEVICE SEMICONDUCTOR
DEVICE MANUFACTURING PROCESS

PRELIMINARY AMENDMENT

Box PCT
To the Assistant Commissioner
for Patents
Washington, D.C. 20231

Sir:

Preliminary to examination of the above-captioned PCT national stage application, kindly amend the application as follows:

In the claims:

Please cancel claims 1 through 16, inclusive, without prejudice or disclaimer and substitute therefor the following new claims 17 through 35:

17. (New) A semiconductor wafer having a roughness of the backside surface varied in a direction of a radius, wherein varied sections exist substantially coaxially in the direction of the radius.

18. (New) A semiconductor wafer having a roughness of the backside surface varied in a direction of a radius, wherein sections of the different